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**Laffon de Mazieres et al.**

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(54) **ELECTRONIC DEVICE CABLE**

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(\*\*) Term: **14 Years**

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(51) **LOC (10) Cl.** ..... **14-02**

(52) **U.S. Cl.**  
USPC ..... **D14/433; D13/154**

(58) **Field of Classification Search**  
USPC ..... D13/147, 154, 153, 139, 156, 133, 108,  
D13/137.2, 139.7, 173; D14/317, 357, 432,  
D14/433, 434, 435.1, 507, 138 C, 356, 142,  
D14/144; 439/887, 352, 607, 502; 361/679  
CPC ..... H01R 31/06  
See application file for complete search history.

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

4,427,256	A *	1/1984	Reif et al.	439/584
D585,835	S *	2/2009	Jaqua et al.	D13/154
D588,545	S *	3/2009	Andre et al.	D13/154
D600,652	S *	9/2009	Hong et al.	D13/154
D620,449	S *	7/2010	Lee et al.	D13/154
D636,337	S *	4/2011	Smith et al.	D13/147
D643,446	S *	8/2011	Gupta et al.	D15/136
D673,908	S *	1/2013	Koch	D13/108
D679,164	S *	4/2013	Chen	D8/70
D680,076	S *	4/2013	McManigal	D13/147
D692,390	S *	10/2013	Smith et al.	D13/153
D699,188	S *	2/2014	Akana et al.	D13/147
D699,686	S *	2/2014	Chen et al.	D13/154
D713,342	S *	9/2014	Jacobs et al.	D13/133
2013/0084760	A1 *	4/2013	Siahaan et al.	439/887
2013/0090020	A1 *	4/2013	Zhang	439/660

**OTHER PUBLICATIONS**

Translated Japanese Office Action mailed Jun. 27, 2014 for Japanese patent application No. 2013-003401, a counterpart foreign application of U.S. Appl. No. 29/430,010, 4 pages.

(Continued)

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(74) *Attorney, Agent, or Firm* — Lee & Hayes, PLLC

(57) **CLAIM**

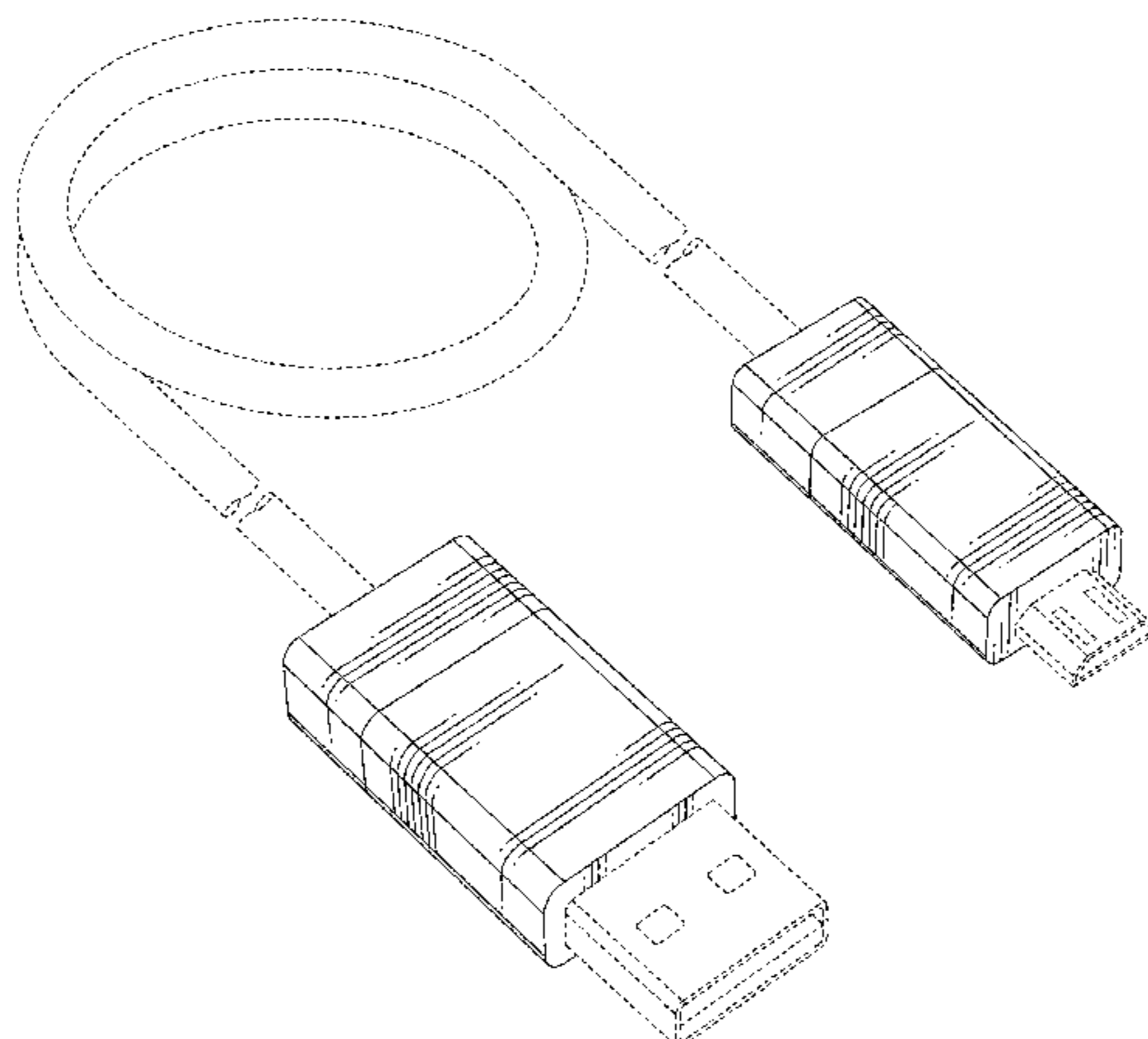
The ornamental design for an electronic device cable, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of an electronic device cable; FIG. 2 is another perspective view of the electronic device cable of FIG. 1; FIG. 3 is a top plan view of the electronic device cable of FIG. 1; FIG. 4 is a bottom plan view of the electronic device cable of FIG. 1; FIG. 5 is a back elevation view of the electronic device cable of FIG. 1; FIG. 6 is a partial cross-sectional view of the electronic device cable of FIG. 1, taken along line 6-6 in FIG. 5; FIG. 7 is a partial cross-sectional view of the electronic device cable of FIG. 1, taken along line 7-7 in FIG. 5; FIG. 8 is a front elevation view of the electronic device cable of FIG. 1; FIG. 9 is a left-side elevation view of the electronic device cable of FIG. 1; and, FIG. 10 is a right-side elevation view of the electronic device cable of FIG. 1.

The broken lines are directed to unclaimed portions and form no part of the claimed design.

**1 Claim, 6 Drawing Sheets**



(56)

**References Cited**

OTHER PUBLICATIONS

Korean Office Action mailed Dec. 19, 2013 for Korean design application No. 30-2013-8579, a counterpart foreign application of design U.S. Appl. No. 29/430,010, 4 pages.

KR Office Action mailed Dec. 19, 2013 for Korean design application No. 30-2013-8583, a counterpart foreign application of design U.S. Appl. No. 29/430,010, 4 pages.  
Translated Japanese Office Action mailed Jan. 10, 2014 for Japanese design application No. 2013-003401, a counterpart foreign application of design U.S. Appl. No. 29/430,010, 4 pages.

\* cited by examiner

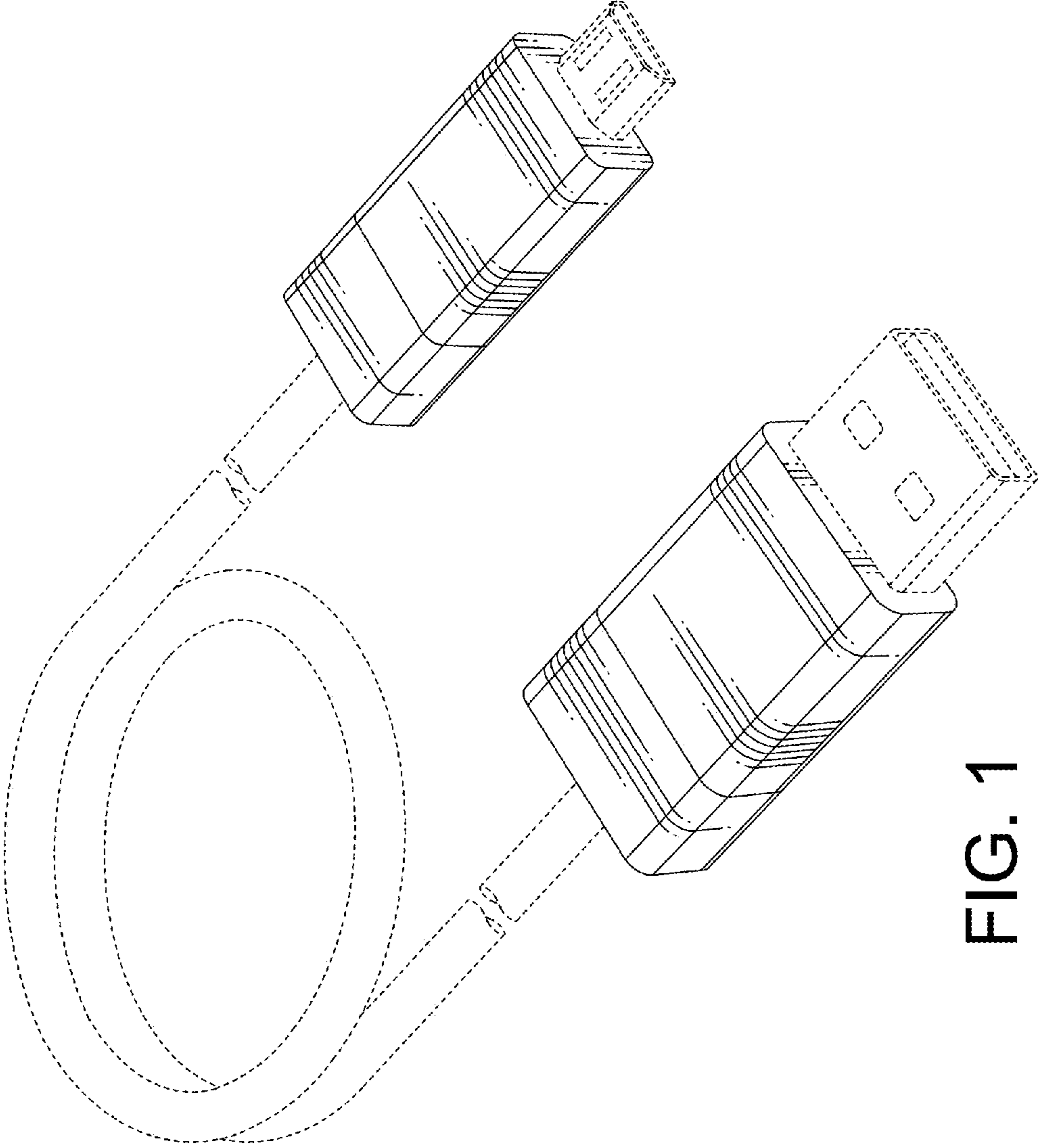


FIG. 1

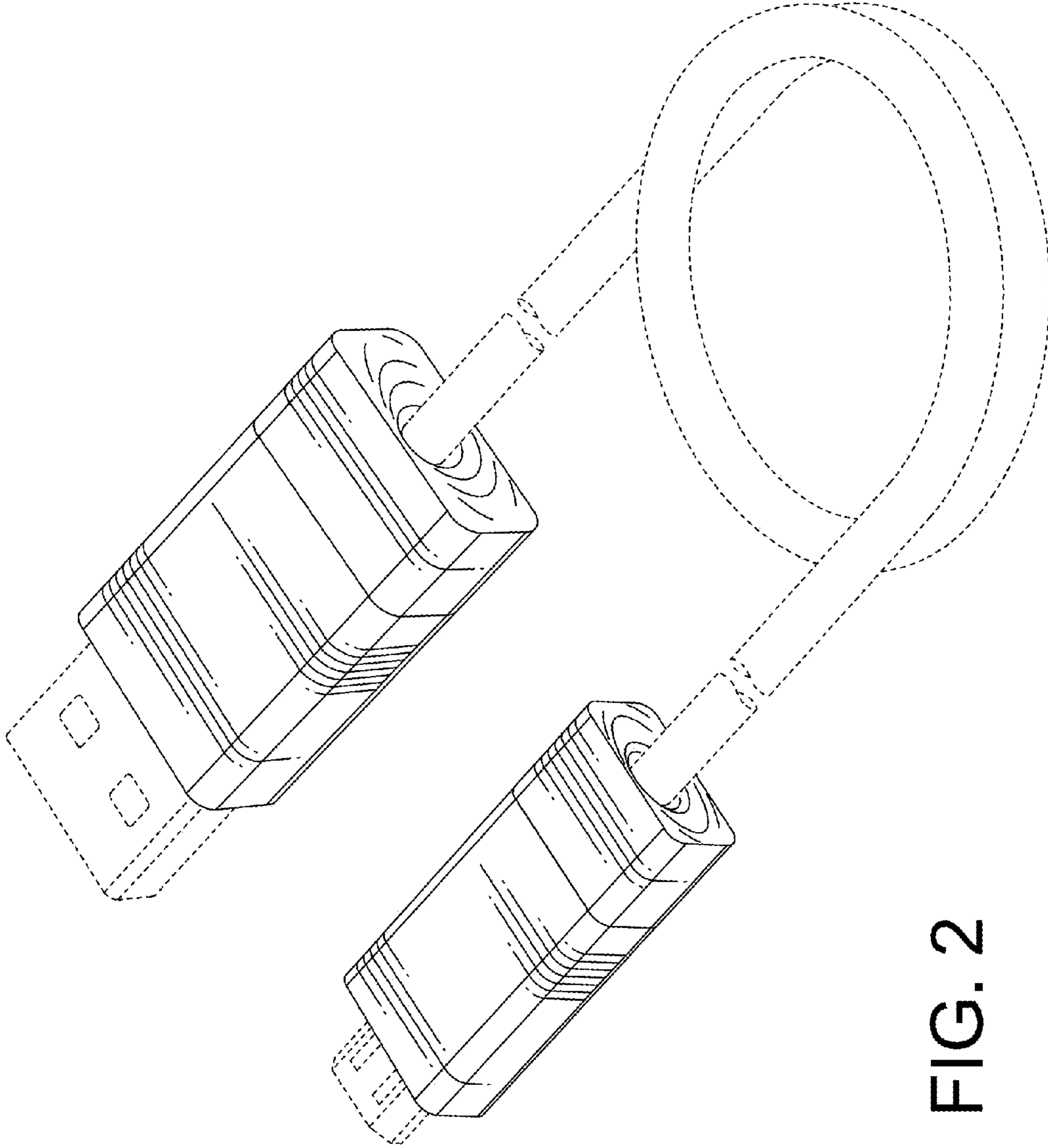


FIG. 2

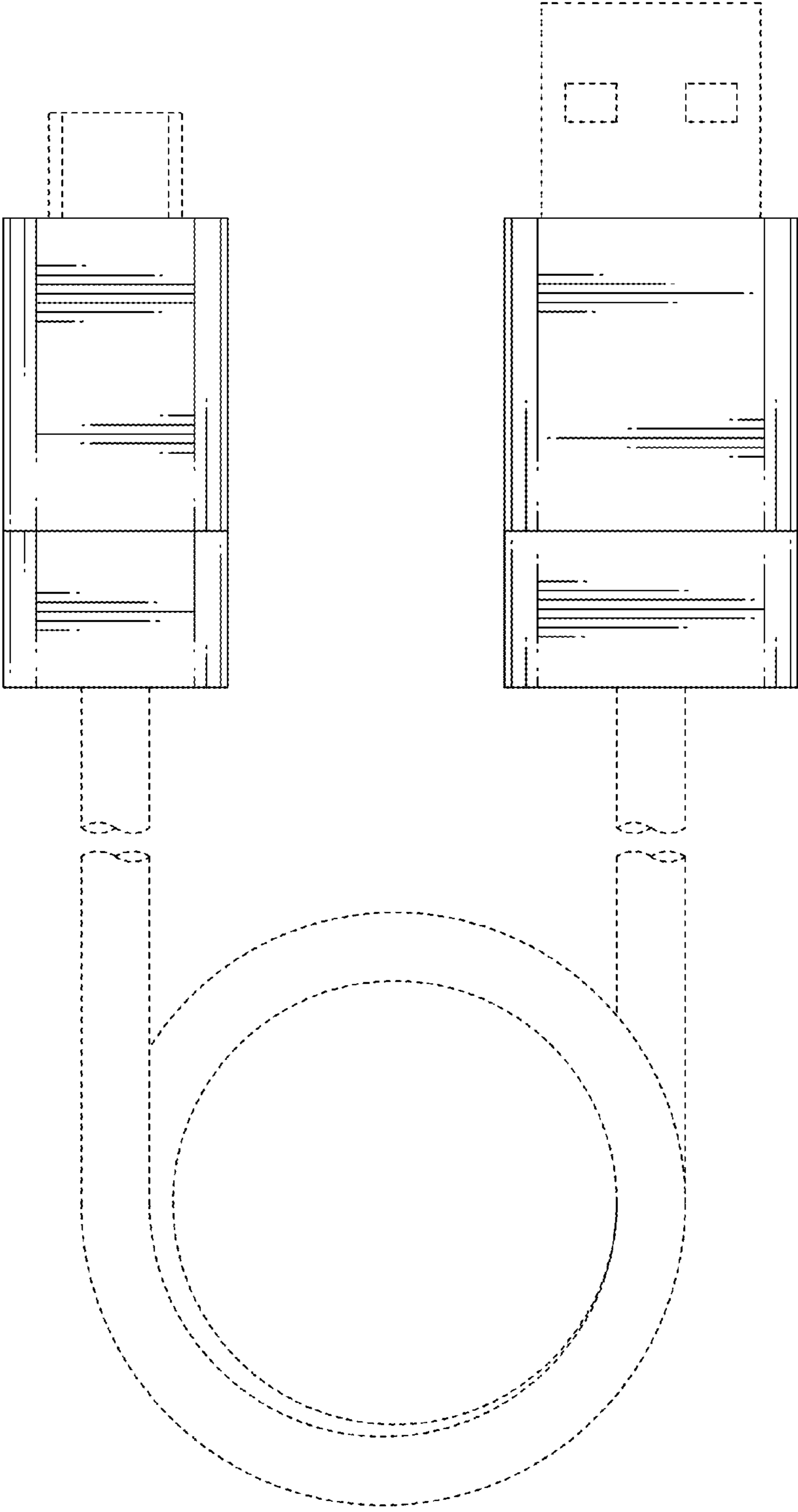


FIG. 3

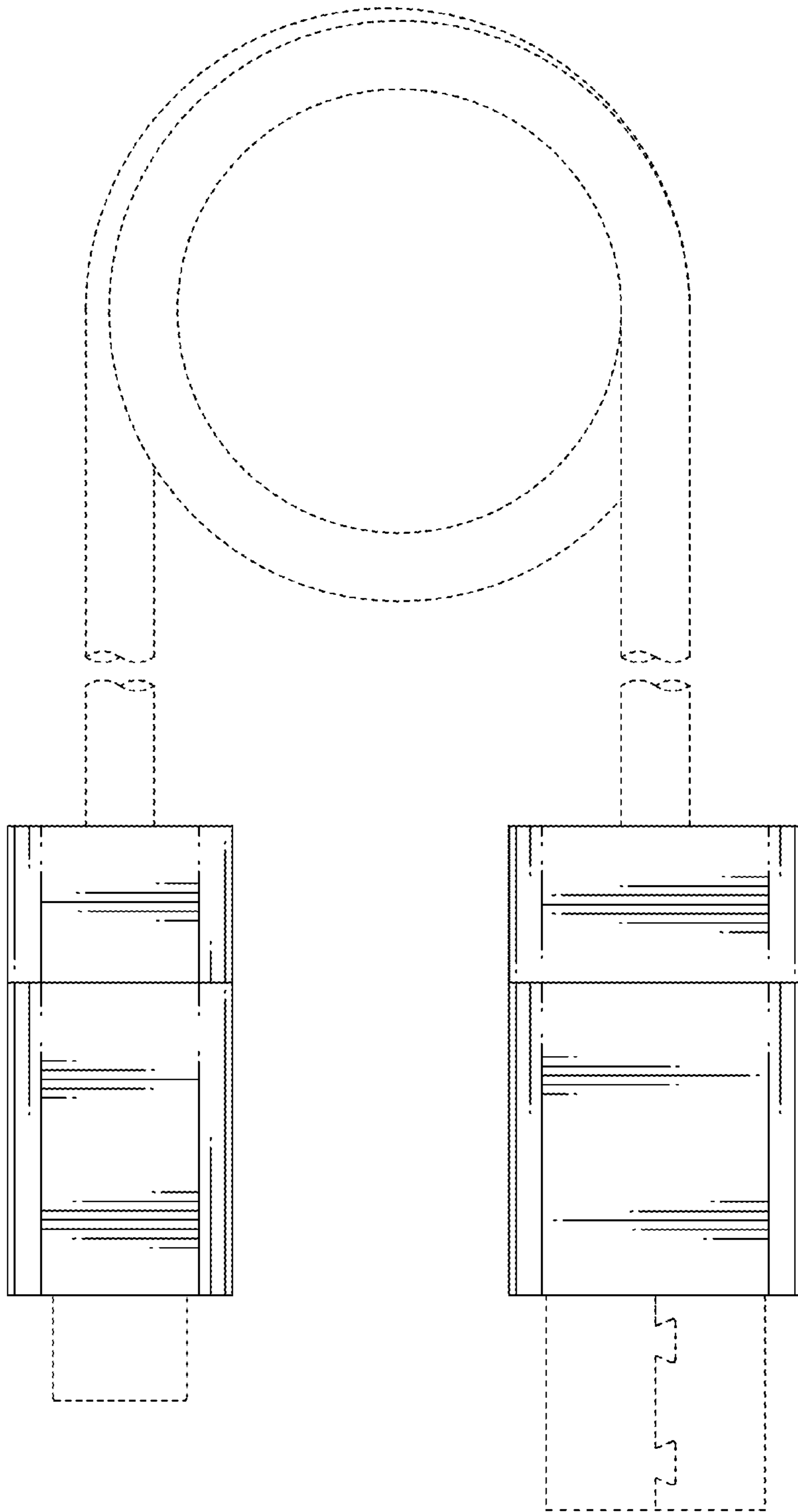


FIG. 4

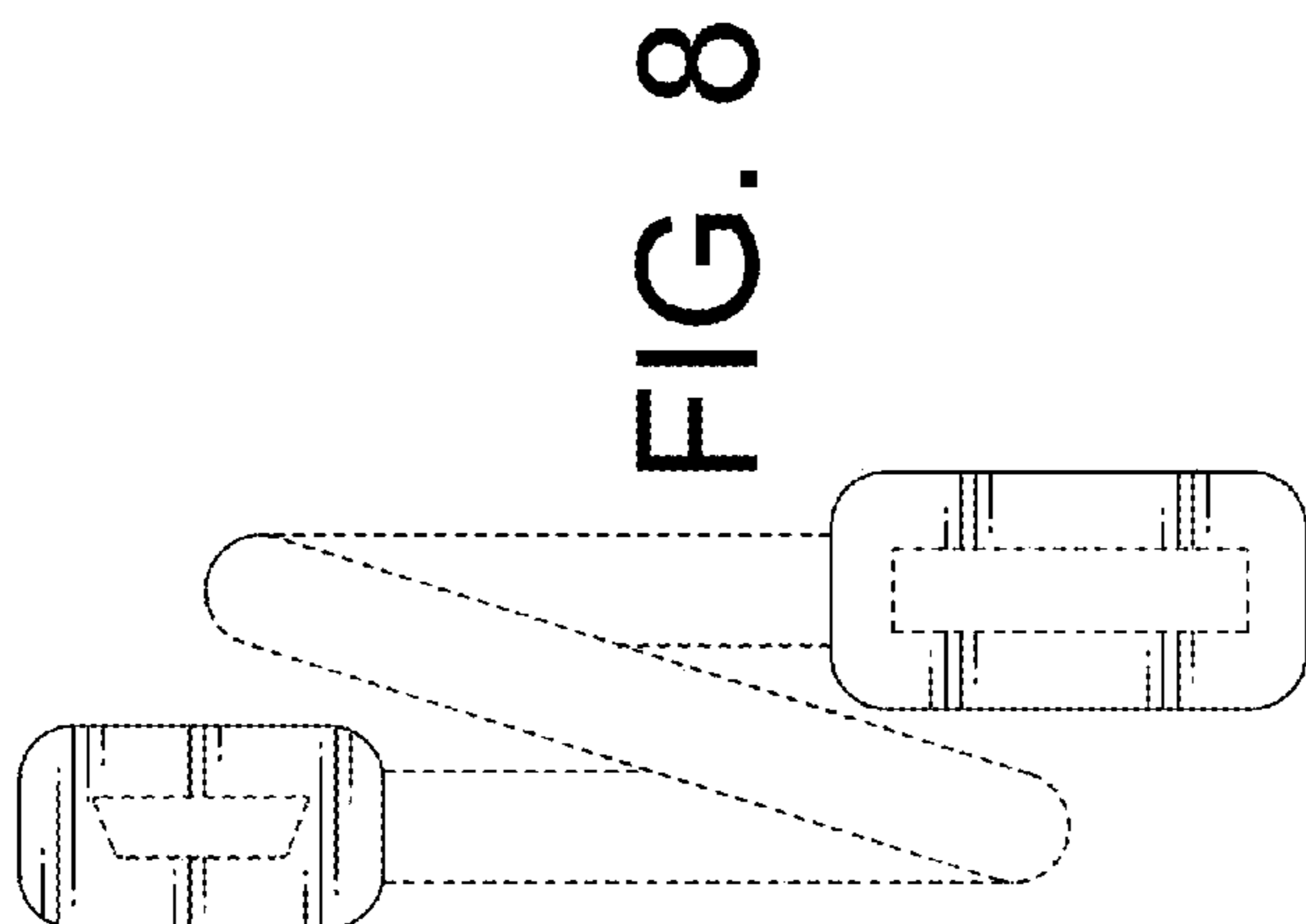


FIG. 8

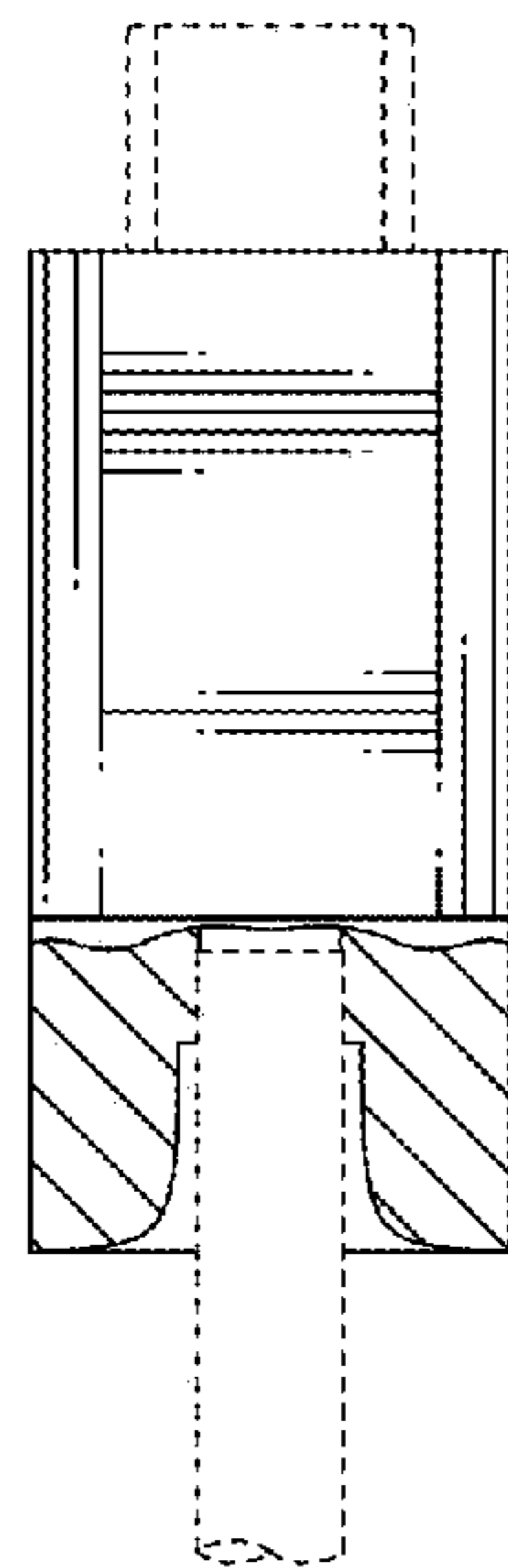


FIG. 7

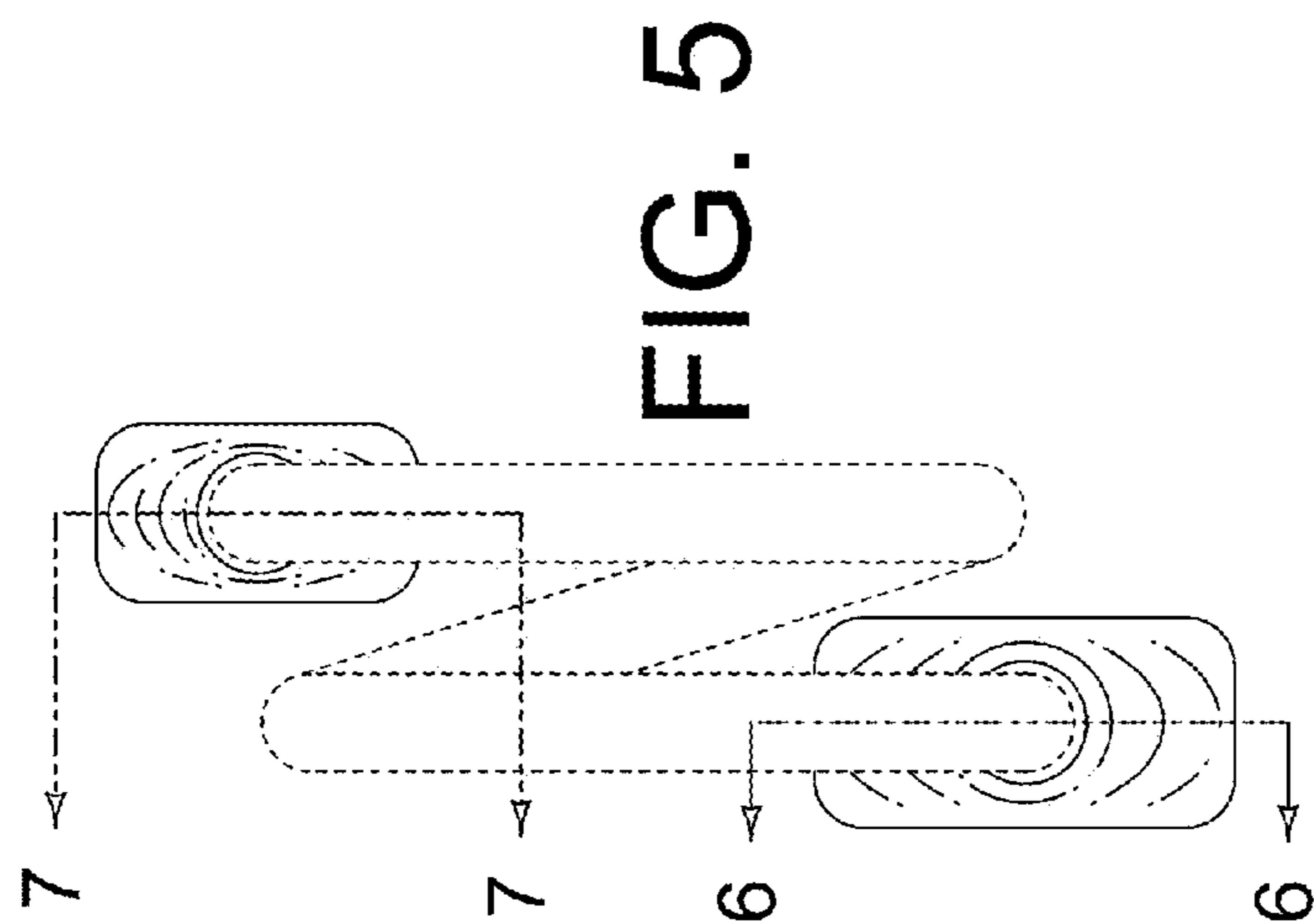


FIG. 5

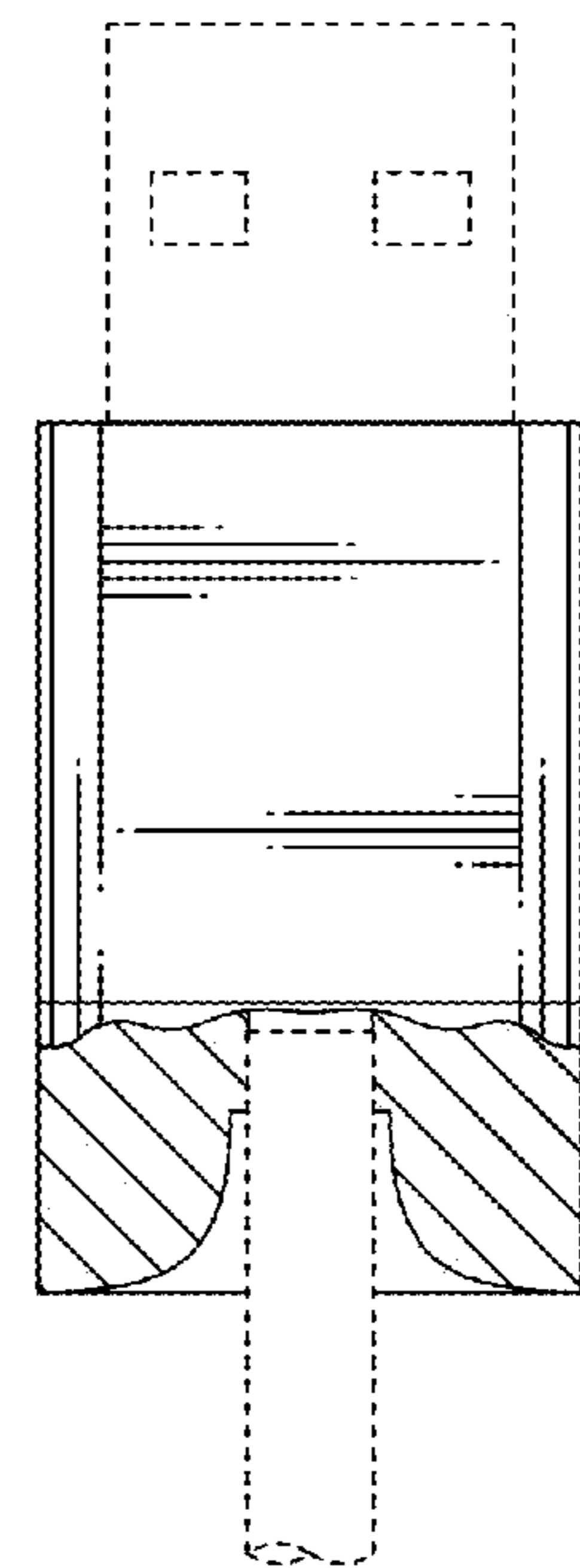


FIG. 6

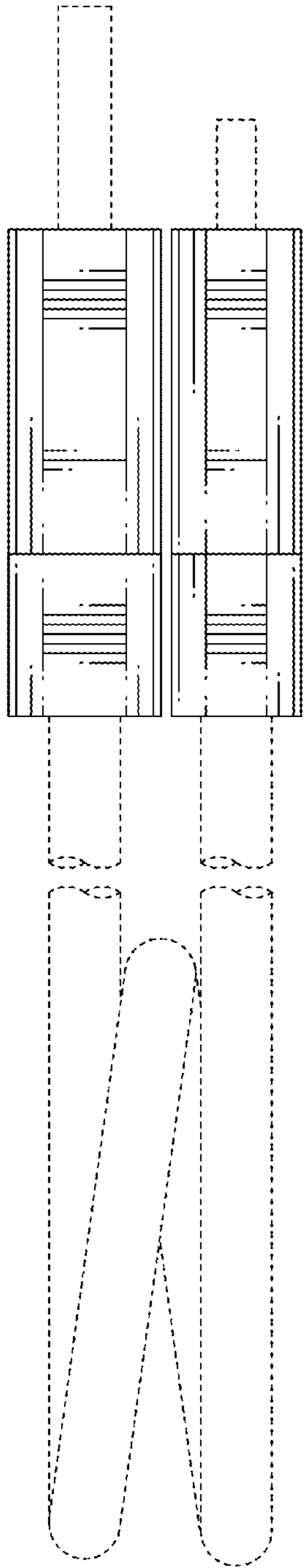


FIG. 9

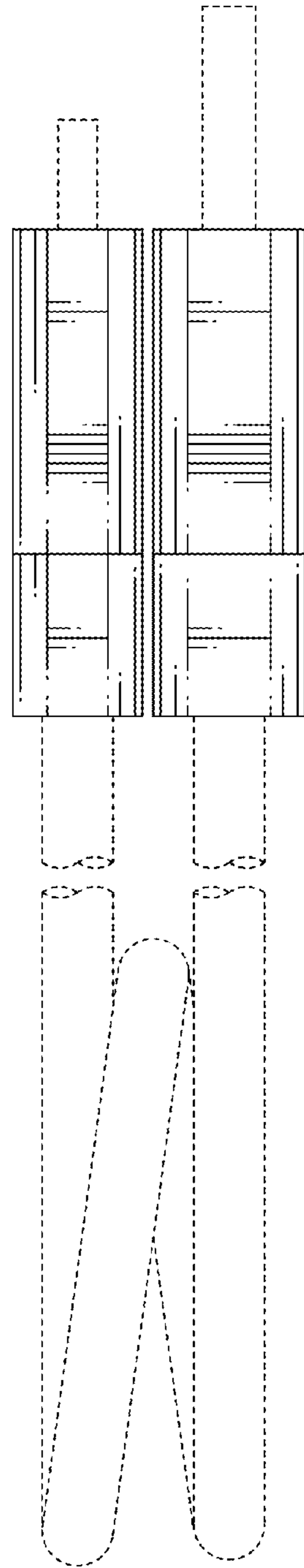


FIG. 10